

Economy Vapour Phase Soldering System for small series and prototyping



Features

- Ideal for prototyping, small series production and rework
- Compact 2-Chamber Soldering System (Table-Top Unit)
- Program storage incl. standard soldering programs
- TE-Option; one thermocouple adapter for profile recording with profiler outside
- Easy Operation with Solder Automatic and Heat Level Adjustment
- Energy management system for lowest energy consumption incl. standby mode
- Lowest fluid consumption due to internal heat exchanger
- Maintenance free transport unit (**Patented**)

Standard Equipment / Specification

- Automatic carrier in- and output
- 2 process chambers with internal air-lock separation
- Observation window into process chamber
- Integrated illumination of the soldering chamber
- Monitoring of cooling water and heating chamber temperature, no overheating
- Automatic fluid filtering and level monitoring
- Integrated cooling blower for board cooling
- Integrated heat exchanger and fluid recovery system
- Variable energy level set-up including program storage
- Automatic or time controlled soldering process (**Patented**)
- Maintenance free transportation system (**Patented**)

Options

- Adapter for double sided PCB board
- ReSy, a device for repair of QFP's and BGA's, (**Patented**)
- Stainless steel grid for work piece carrier
- Cooling device for closed loop machine cooling
- TE-Option for external profile monitoring

Overview

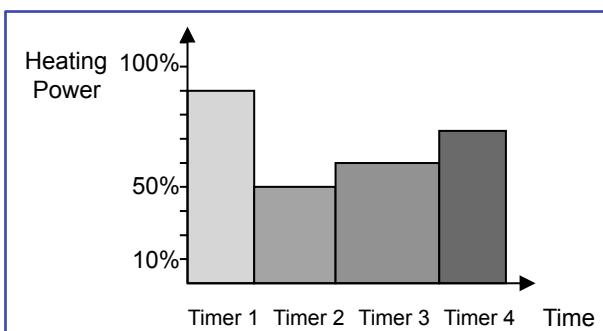
The SV 260 is a fully operational vapour phase soldering system with conveniently compact footprint.

The 2 chamber system in combination with the frontloading allows a comfortable operation. This supports high operational quality standards as well as high throughput.

Modes of operation

Heat Level Mode (HL-Mode)

A simple variation of vapour phases soldering, generates different, nearly linear temperature profiles. Energy transfer is controlled by adjustable heating power.



Solder Automatic

For the optimization of the solder-process the integrated standard-solder-automatic can be activated in addition. This automatically controls the adaptation of the solder time.

Technical Data SV 260

Width	760 mm
Depth	710 mm
Height	600 mm
Weight	90 kg
max. PCB size	300 x 260 x 80 mm
Soldering fluid filling (min.)	3 kg
Water connection	1/2"
Max. heating capacity	2.1 kW
Ø power consumption	0.9 kWh
Power supply / Main fuse	230 VAC, 2.2 kW/ 16 A, Type "gL" or "C"

- Technical changes reserved -